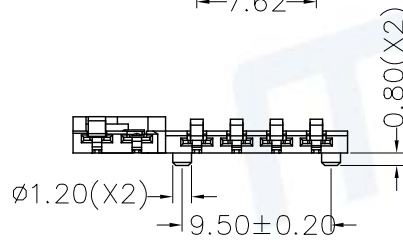
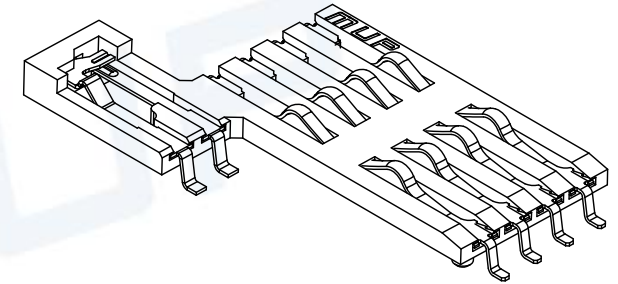
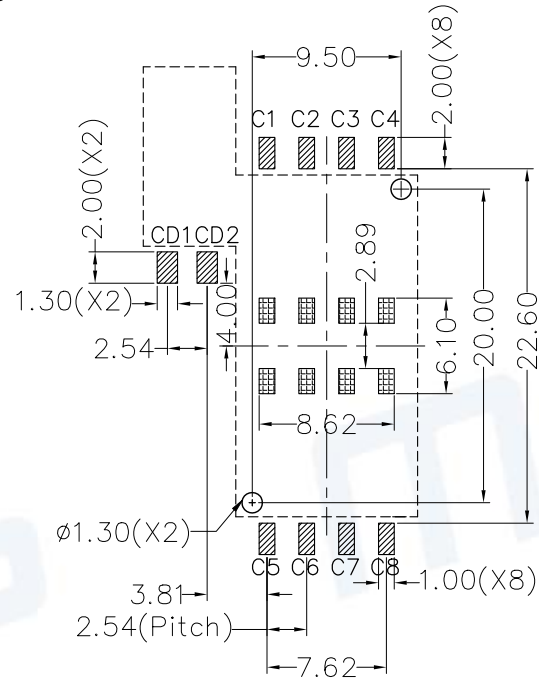
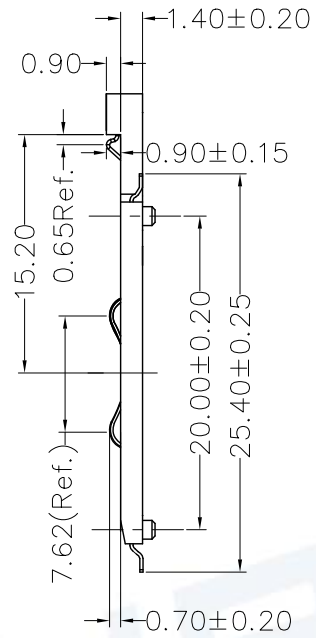
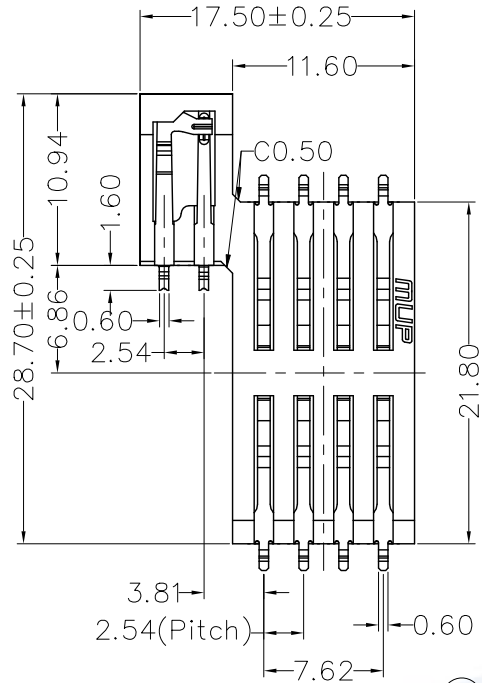


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



RECOMMENDED P.C.B LAYOUT  
 COMPONENT SIDE(TOLERANCE ±0.05)  
 ▨ PAD AREA    ▩ KEEP OUT AREA  
 Coplanarity of metal solder pins  $\leq 0.15\text{mm}$   
 Recommending of solder paste thickness  $> 0.15\text{mm}$

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 28.70LX17.50WX1.40 mm  
 Weight: Approx 0.63±0.1g  
 Durability: 100,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max  
 Insulation resistance: >1000MΩ/500V DC

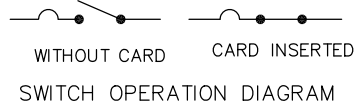
3.Solderability

IR reflow: 260°C, 10sec.Max  
 Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C  
 Operating humidity: 10%~+95%RH

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	OPEN
CARD INSERTED	CLOSED



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SWITCH CONTACT 2	1	Copper Alloy	Contact area:Gold plated
4	SWITCH CONTACT 1	1	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **Smart Card Connector**

MODEL NO: **MUP-C735-1**

TYPE: **with post(H1.40 mm)**

PROJ.	UNIT	SCALE	DRAWN	Zoey Oct.10.2007	DWG NO.:	DWG-MUP-C735-1
①	mm	1:1	CHECKED	Keey Oct.10.2007	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Simon Oct.10.2007	REVISION	X2

